

FEB. 26. 2004 2:55PM

MBS&S 919 854-1401

NO. 7409 P. 10

Attorney Docket No. 5649-968

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**RECEIVED
CENTRAL FAX CENTER**

MAR 25 2004

In re: Lee et al.

Serial No.: 10/046,805

Filed: January 14, 2002

For: METHODS OF FORMING METAL LAYERS IN INTEGRATED CIRCUIT
DEVICES USING SELECTIVE ELECTROPLATING ON EDGES OF
RECESSES AND CONDUCTIVE CONTACTS SO FORMED

Group Art Unit: 2829

Examiner: Lisa A. Kilday

Confirmation No.: 6423

OFFICIAL

January 9, 2004

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

**AMENDMENT AND SUBMISSION OF TERMINAL DISCLAIMER WITH
INFORMATION DISCLOSURE STATEMENT**

Sir:

This Amendment and Submission is responsive to the Official Action of July
9, 2003.

Amendments to the Claims are reflected in the listing of claims, which
begins on page 2 of this paper.

Remarks begin on page 6 of this paper.